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Box Patent Applications  
Assistant Commissioner for Patents  
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No. : DP-305031

Inventor(s) : Shing Yeh  
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Title : LEAD-FREE SOLDER ALLOY AND SOLDER REFLOW PROCESS

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Enclosures

I hereby certify that this document is being deposited with the United States Postal Service with sufficient postage as Express Mail addressed to Box Missing Parts, Assistant Commissioner for Patents, Washington, D.C. 20231 on March 15, 2002. Express Mail Label EK877647791US

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